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(3) s

Schematic diagram

NCE

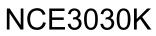
NCE3030K

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Marking and pin Assignment

TO-252-2L top view

(1) G C



NCE N-Channel Enhancement Mode Power MOSFET

DESCRIPTION

The NCE3030K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

GENERAL FEATURES

- V_{DS} =30V,I_D =30A
 R_{DS(ON)} <20mΩ @ V_{GS}=10V
- High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

100% UIS TESTED!

100% ΔVds TESTED!

Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE3030K	NCE3030K	TO-252-2L	-	-	-

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	ID	30	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	21	A
Pulsed Drain Current	I _{DM}	80	A
Maximum Power Dissipation	PD	30	W
Derating factor		0.2	W/°C
Single pulse avalanche energy (Note 5)	E _{AS}	72	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	°C

Thermal Characteristic



Pb Free Product

5.1

NCE3030K

Thermal Resistance, Junction-to-Case(Note 2)

R_{ejc}

°C/W

Electrical Characteristics (TC=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			•
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.9	3.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =15A	-	18	22	mΩ
Forward Transconductance	g fs	V _{DS} =5V,I _D =20A	26	-	-	S
Dynamic Characteristics (Note4)	·		·			
Input Capacitance	Clss		-	938	-	PF
Output Capacitance	C _{oss}	V_{DS} =15V, V_{GS} =0V,	-	142	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	99	-	PF
Switching Characteristics (Note 4)	·	·	•			•
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	V_{DD} =15V, R _L =0.75 Ω	-	12	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10V, R_{G} =3 Ω	-	19	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	V -15V/L -20A	-	17.5		nC
Gate-Source Charge	Q _{gs}	V _{DS} =15V,I _D =20A, V _{GS} =10V	-	3		nC
Gate-Drain Charge	Q _{gd}	V _{GS} -IUV	-	4.1		nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	I _S		-	-	20	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF =20A	-	19	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs(Note3) - 10		-	nC	
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

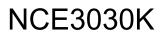
4. Guaranteed by design, not subject to production

5. EAS condition: Tj=25 $^\circ \!\! \mathbb{C}, V_{DD} \!\! = \! 30V, V_G \!\! = \! 10V, L \!\! = \! 0.5mH, Rg \!\! = \! 25\Omega$



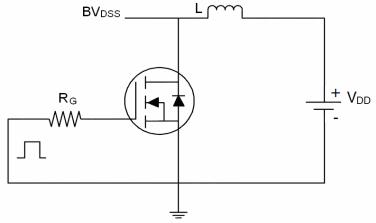
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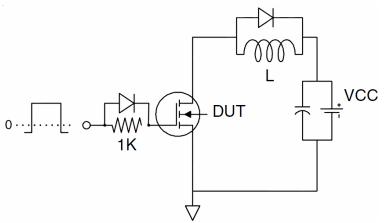


Test circuit

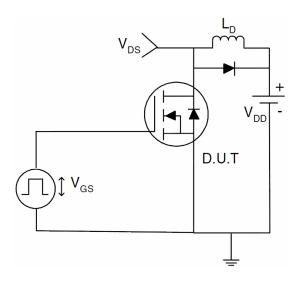
1) E_{AS} test Circuits



2) Gate charge test Circuit:



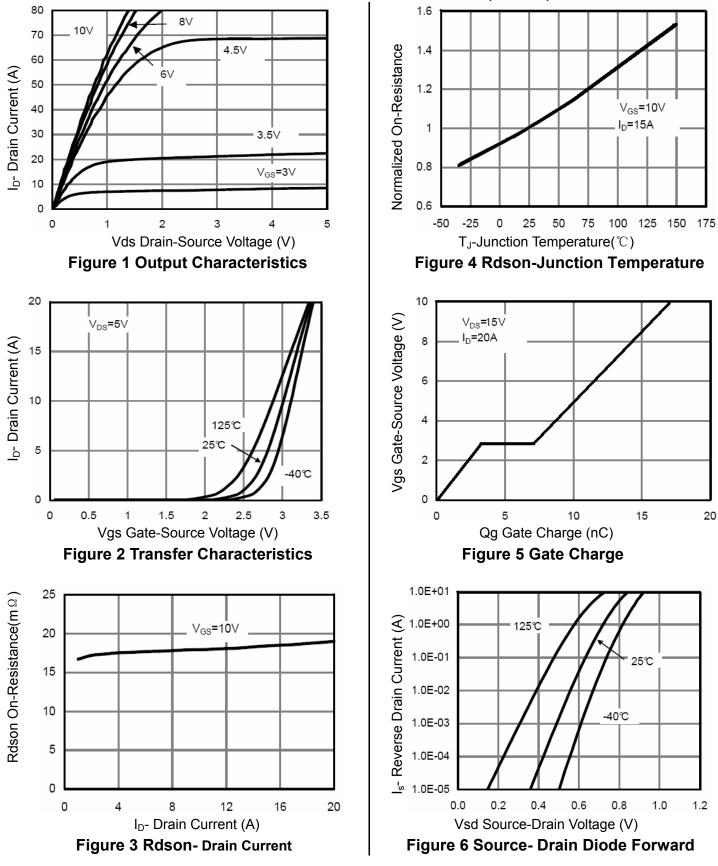
3) Switch Time Test Circuit:





NCE3030K

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

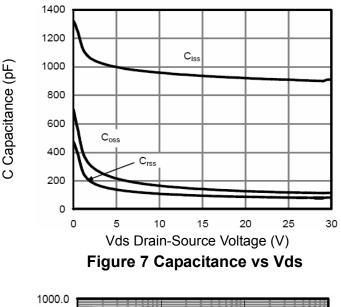




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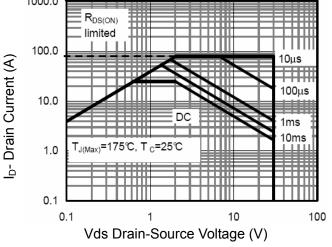


Figure 8 Safe Operation Area

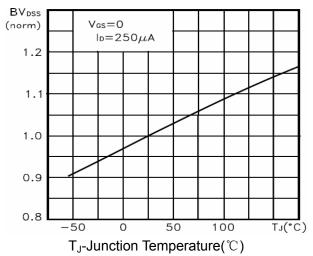


Figure 9 BV_{DSS} vs Junction Temperature

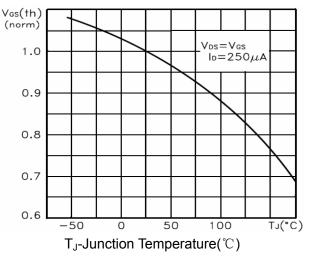
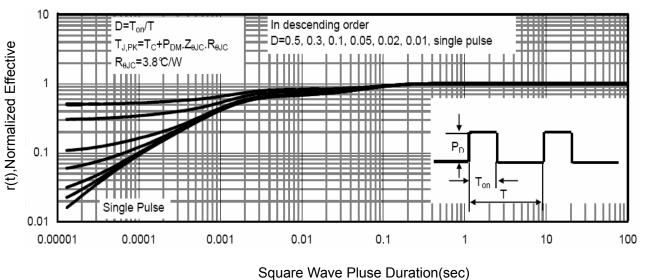
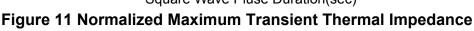


Figure 10 V_{GS(th)} vs Junction Temperature

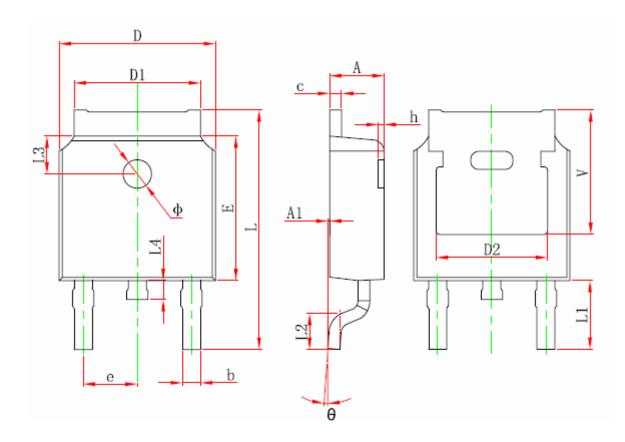








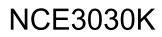
TO-252-2L Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
с	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	REF.	0.190 REF.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 REF.		0.114 REF.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	REF.	0.063 REF.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	REF.	0.211 REF.		







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